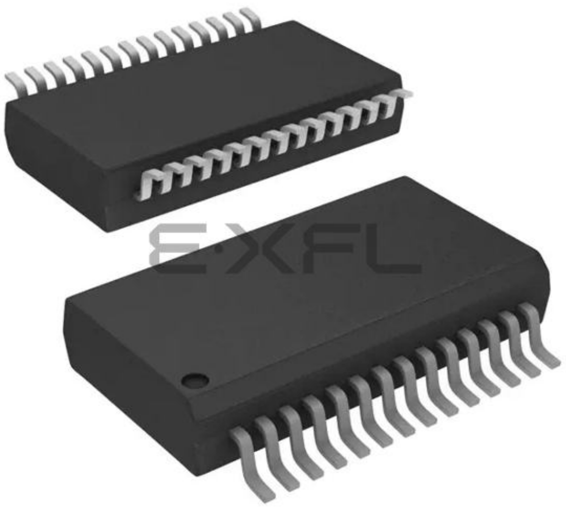

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f76t-e-ss

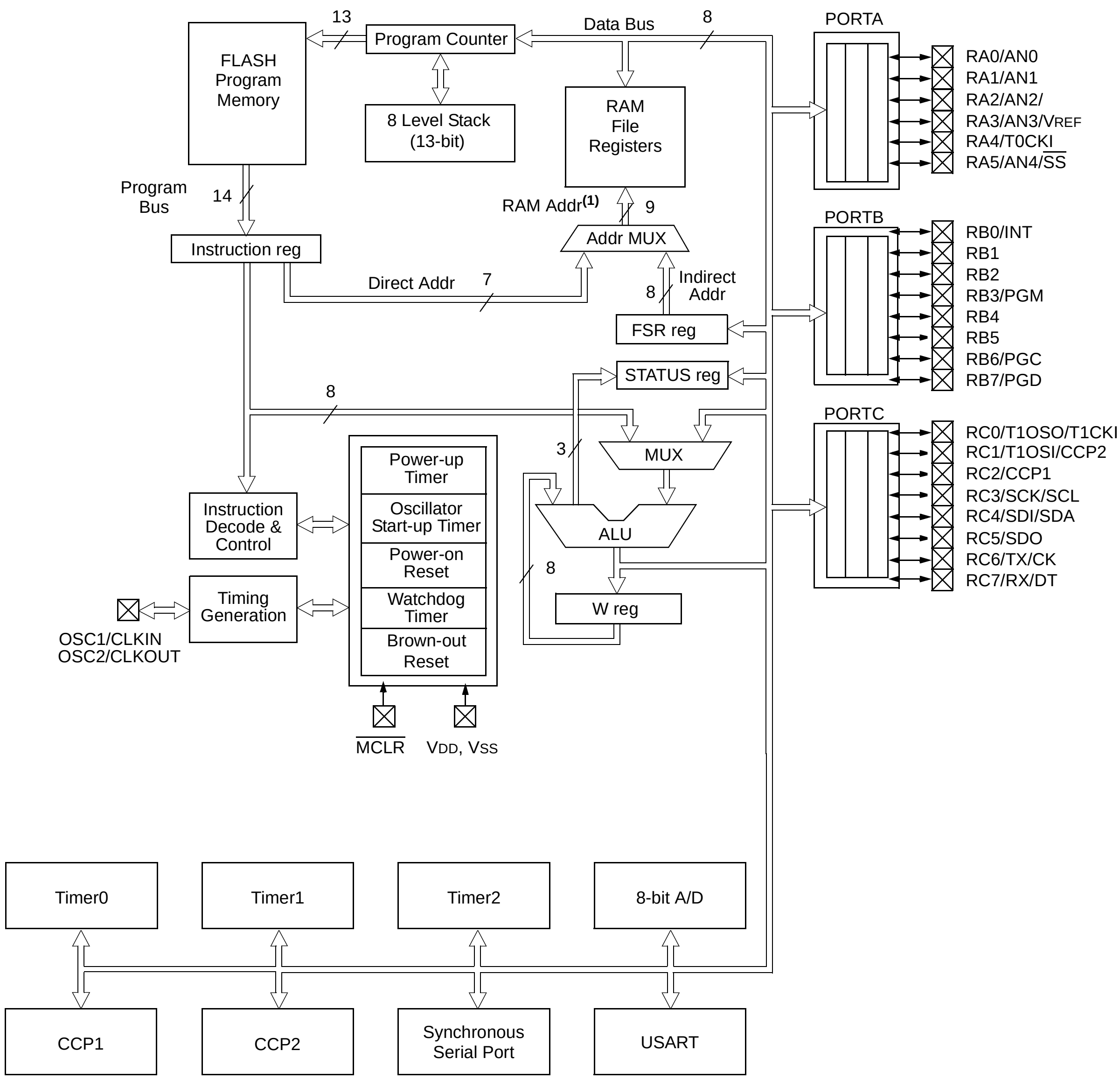
Note the following details of the code protection feature on PICmicro® MCUs.

- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable”.
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

If you have any further questions about this matter, please contact the local sales office nearest to you.

Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company’s quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip’s quality system for the design and manufacture of development systems is ISO 9001 certified.

FIGURE 1-1: PIC16F73 AND PIC16F76 BLOCK DIAGRAM



Device	Program FLASH	Data Memory
PIC16F73	4K	192 Bytes
PIC16F76	8K	368 Bytes

Note 1: Higher order bits are from the STATUS register.

TABLE 1-2: PIC16F73 AND PIC16F76 PINOUT DESCRIPTION (CONTINUED)

Pin Name	DIP SSOP SOIC Pin#	MLF Pin#	I/O/P Type	Buffer Type	Description
					PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	21	18		TTL/ST(1)	
RB0			I/O		Digital I/O.
INT			I		External interrupt.
RB1	22	19	I/O	TTL	Digital I/O.
RB2	23	20	I/O	TTL	Digital I/O.
RB3/PGM	24	21		TTL	
RB3			I/O		Digital I/O.
PGM			I/O		Low voltage ICSP programming enable pin.
RB4	25	22	I/O	TTL	Digital I/O.
RB5	26	23	I/O	TTL	Digital I/O.
RB6/PGC	27	24		TTL/ST(2)	
RB6			I/O		Digital I/O.
PGC			I/O		In-Circuit Debugger and ICSP programming clock.
RB7/PGD	28	25		TTL/ST(2)	
RB7			I/O		Digital I/O.
PGD			I/O		In-Circuit Debugger and ICSP programming data.
					PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	11	8		ST	
RC0			I/O		Digital I/O.
T1OSO			O		Timer1 oscillator output.
T1CKI			I		Timer1 external clock input.
RC1/T1OSI/CCP2	12	9		ST	
RC1			I/O		Digital I/O.
T1OSI			I		Timer1 oscillator input.
CCP2			I/O		Capture2 input, Compare2 output, PWM2 output.
RC2/CCP1	13	10		ST	
RC2			I/O		Digital I/O.
CCP1			I/O		Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	14	11		ST	
RC3			I/O		Digital I/O.
SCK			I/O		Synchronous serial clock input/output for SPI mode.
SCL			I/O		Synchronous serial clock input/output for I^2C mode.
RC4/SDI/SDA	15	12		ST	
RC4			I/O		Digital I/O.
SDI			I		SPI data in.
SDA			I/O		I^2C data I/O.
RC5/SDO	16	13		ST	
RC5			I/O		Digital I/O.
SDO			O		SPI data out.
RC6/TX/CK	17	14		ST	
RC6			I/O		Digital I/O.
TX			O		USART asynchronous transmit.
CK			I/O		USART 1 synchronous clock.
RC7/RX/DT	18	15		ST	
RC7			I/O		Digital I/O.
RX			I		USART asynchronous receive.
DT			I/O		USART synchronous data.
VSS	8, 19	5, 16	P	—	Ground reference for logic and I/O pins.
VDD	20	17	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.

3.0 READING PROGRAM MEMORY

The FLASH Program Memory is readable during normal operation over the entire VDD range. It is indirectly addressed through Special Function Registers (SFR). Up to 14-bit numbers can be stored in memory for use as calibration parameters, serial numbers, packed 7-bit ASCII, etc. Executing a program memory location containing data that forms an invalid instruction results in a NOP.

There are five SFRs used to read the program and memory. These registers are:

- PMCON1
- PMDATA
- PMDATH
- PMADR
- PMADRH

The program memory allows word reads. Program memory access allows for checksum calculation and reading calibration tables.

When interfacing to the program memory block, the PMDATH:PMDATA registers form a two-byte word, which holds the 14-bit data for reads. The PMADRH:PMADR registers form a two-byte word, which holds the 13-bit address of the FLASH location being accessed. These devices can have up to 8K words of program FLASH, with an address range from 0h to 3FFFh. The unused upper bits in both the PMDATH and PMADRH registers are not implemented and read as “0’s”.

3.1 PMADR

The address registers can address up to a maximum of 8K words of program FLASH.

When selecting a program address value, the MSByte of the address is written to the PMADRH register and the LSByte is written to the PMADR register. The upper MSbits of PMADRH must always be clear.

3.2 PMCON1 Register

PMCON1 is the control register for memory accesses.

The control bit RD initiates read operations. This bit cannot be cleared, only set, in software. It is cleared in hardware at the completion of the read operation.

REGISTER 3-1: PMCON1 REGISTER (ADDRESS 18Ch)

R-1	U-0	U-0	U-0	U-x	U-0	U-0	R/S-0
reserved	—	—	—	—	—	—	RD
bit 7							bit 0

bit 7 **Reserved:** Read as ‘1’

bit 6-1 **Unimplemented**: Read as '0'

bit 0 **RD**: Read Control bit
1 = Initiates a FLASH read, RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
0 = FLASH read completed

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR reset	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

3.3 Reading the FLASH Program Memory

A program memory location may be read by writing two bytes of the address to the PMADR and PMADRH registers and then setting control bit RD (PMCON1<0>). Once the read control bit is set, the microcontroller will use the next two instruction cycles to read the data. The data is available in the PMDATA and PMDATH registers after the second NOP instruction. Therefore, it can be read as two bytes in the following instructions. The PMDATA and PMDATH registers will hold this value until the next read operation.

3.4 Operation During Code Protect

FLASH program memory has its own code protect mechanism. External Read and Write operations by programmers are disabled if this mechanism is enabled.

The microcontroller can read and execute instructions out of the internal FLASH program memory, regardless of the state of the code protect configuration bits.

EXAMPLE 3-1: FLASH PROGRAM READ

```
            BSF     STATUS, RP1     ;
            BCF     STATUS, RP0     ; Bank 2
            MOVF    ADDRH, W        ;
            MOVWF   PMADRH          ; MSByte of Program Address to read
            MOVF    ADDRL, W        ;
            MOVWF   PMADR           ; LSByte of Program Address to read
            BSF     STATUS, RP0     ; Bank 3 Required

Required    BSF     PMCON1, RD      ; EEPROM Read Sequence
Sequence    NOP                     ; memory is read in the next two cycles after BSF PMCON1,RD
            NOP                     ;

            BCF     STATUS, RP0     ; Bank 2
            MOVF    PMDATA, W       ; W = LSByte of Program PMDATA
            MOVF    PMDATH, W       ; W = MSByte of Program PMDATA
```

TABLE 3-1: REGISTERS ASSOCIATED WITH PROGRAM FLASH

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
10Dh	PMADR	Address Register Low Byte								xxxx xxxx	uuuu uuuu
10Fh	PMADRH	—	—	—	Address Register High Byte					xxxx xxxx	uuuu uuuu
10Ch	PMDATA	Data Register Low Byte								xxxx xxxx	uuuu uuuu
10Eh	PMDATH	—	—	Data Register High Byte						xxxx xxxx	uuuu uuuu
18Ch	PMCON1	—(1)	—	—	—	—	—	—	RD	1--- ---0	1--- ---0

Legend: x = unknown, u = unchanged, r = reserved, - = unimplemented read as '0'. Shaded cells are not used during FLASH access.
Note 1: This bit always reads as a ‘1’.

8.5.3 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
3. Make the CCP1 pin an output by clearing the TRISC<2> bit.
4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
5. Configure the CCP1 module for PWM operation.

TABLE 8-4: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 20 MHz)

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

TABLE 8-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh	PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
11h	TMR2	Timer2 Module Register								0000 0000	0000 0000
92h	PR2	Timer2 Module Period Register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM Register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh	CCPR2L	Capture/Compare/PWM Register2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch	CCPR2H	Capture/Compare/PWM Register2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PWM and Timer2.
Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F73/76; always maintain these bits clear.

9.3.2 MASTER MODE

Master mode of operation is supported in firmware using interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a RESET or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I^2C bus may be taken when the P bit is set, or the bus is IDLE and both the S and P bits are clear.

In Master mode, the SCL and SDA lines are manipulated by clearing the corresponding TRISC<4:3> bit(s). The output level is always low, irrespective of the value(s) in PORTC<4:3>. So when transmitting data, a '1' data bit must have the TRISC<4> bit set (input) and a '0' data bit must have the TRISC<4> bit cleared (output). The same scenario is true for the SCL line with the TRISC<3> bit. Pull-up resistors must be provided externally to the SCL and SDA pins for proper operation of the I^2C module.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt will occur if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received

Master mode of operation can be done with either the Slave mode IDLE (SSPM3:SSPM0 = `1011`), or with the Slave active. When both Master and Slave modes are enabled, the software needs to differentiate the source(s) of the interrupt.

9.3.3 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the START and STOP conditions, allows the determination of when the bus is free. The STOP (P) and START (S) bits are cleared from a RESET or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I^2C bus may be taken when bit P (SSPSTAT<4>) is set, or the bus is IDLE and both the S and P bits clear. When the bus is busy, enabling the SSP Interrupt will generate the interrupt when the STOP condition occurs.

In Multi-Master operation, the SDA line must be monitored to see if the signal level is the expected output level. This check only needs to be done when a high level is output. If a high level is expected and a low level is present, the device needs to release the SDA and SCL lines (set TRISC<4:3>). There are two stages where this arbitration can be lost, these are:

- Address Transfer
- Data Transfer

When the slave logic is enabled, the slave continues to receive. If arbitration was lost during the address transfer stage, communication to the device may be in progress. If addressed, an $\overline{ACK}$ pulse will be generated. If arbitration was lost during the data transfer stage, the device will need to retransfer the data at a later time.

TABLE 9-3: REGISTERS ASSOCIATED WITH I^2C OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
93h	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	0000 0000
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP(2)	CKE(2)	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented locations read as '0'. Shaded cells are not used by SSP module in I^2C mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16F73/76; always maintain these bits clear.

2: Maintain these bits clear in I^2C mode.

NOTES:

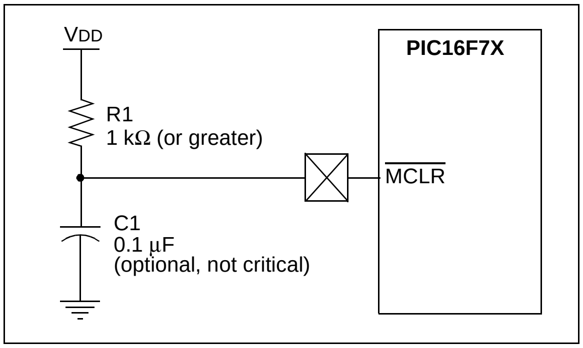
12.4 $\overline{\text{MCLR}}$

PIC16F7X devices have a noise filter in the $\overline{\text{MCLR}}$ Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{\text{MCLR}}$ pin low.

The behavior of the ESD protection on the $\overline{\text{MCLR}}$ pin has been altered from previous devices of this family. Voltages applied to the pin that exceed its specification can result in both $\overline{\text{MCLR}}$ Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the $\overline{\text{MCLR}}$ pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 12-5, is suggested.

FIGURE 12-5: RECOMMENDED $\overline{\text{MCLR}}$ CIRCUIT



12.5 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, tie the $\overline{\text{MCLR}}$ pin to VDD as described in Section 12.4. A maximum rise time for VDD is specified. See the Electrical Specifications for details.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met. For additional information, refer to Application Note, AN607, “Power-up Trouble Shooting” (DS00607).

12.6 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT’s time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip, due to VDD, temperature and process variation. See DC parameters for details (TPWRT, parameter #33).

12.7 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycles (from OSC1 input) delay after the PWRT delay is over (if enabled). This helps to ensure that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset, or wake-up from SLEEP.

12.8 Brown-out Reset (BOR)

The configuration bit, BODEN, can enable or disable the Brown-out Reset circuit. If VDD falls below VBOR (parameter D005, about 4V) for longer than TBOR (parameter #35, about 100 µS), the brown-out situation will reset the device. If VDD falls below VBOR for less than TBOR, a RESET may not occur.

Once the brown-out occurs, the device will remain in Brown-out Reset until VDD rises above VBOR. The Power-up Timer then keeps the device in RESET for TPWRT (parameter #33, about 72 mS). If VDD should fall below VBOR during TPWRT, the Brown-out Reset process will restart when VDD rises above VBOR, with the Power-up Timer Reset. The Power-up Timer is always enabled when the Brown-out Reset circuit is enabled, regardless of the state of the PWRT configuration bit.

12.9 Time-out Sequence

On power-up, the time-out sequence is as follows: the PWRT delay starts (if enabled) when a POR Reset occurs. Then, OST starts counting 1024 oscillator cycles when PWRT ends (LP, XT, HS). When the OST ends, the device comes out of RESET.

If $\overline{\text{MCLR}}$ is kept low long enough, all delays will expire. Bringing $\overline{\text{MCLR}}$ high will begin execution immediately. This is useful for testing purposes or to synchronize more than one PIC16F7X device operating in parallel.

Table 12-5 shows the RESET conditions for the STATUS, PCON and PC registers, while Table 12-6 shows the RESET conditions for all the registers.

TABLE 12-6: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Devices				Power-on Reset, Brown-out Reset	MCLR Reset, WDT Reset	Wake-up via WDT or Interrupt
PIE2	73	74	76	77	---- ---0	---- ---0	---- ---u
PCON	73	74	76	77	---- --qq	---- --uu	---- --uu
PR2	73	74	76	77	1111 1111	1111 1111	1111 1111
SSPSTAT	73	74	76	77	--00 0000	--00 0000	--uu uuuu
SSPADD	73	74	76	77	0000 0000	0000 0000	uuuu uuuu
TXSTA	73	74	76	77	0000 -010	0000 -010	uuuu -uuu
SPBRG	73	74	76	77	0000 0000	0000 0000	uuuu uuuu
ADCON1	73	74	76	77	---- -000	---- -000	---- -uuu
PMDATA	73	74	76	77	0--- 0000	0--- 0000	u--- uuuu
PMADR	73	74	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PMDATH	73	74	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PMADRH	73	74	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PMCON1	73	74	76	77	1--- ---0	1--- ---0	1--- ---u

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition, r = reserved, maintain clear

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 12-5 for RESET value for specific condition.

FIGURE 12-6: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD THROUGH RC NETWORK)

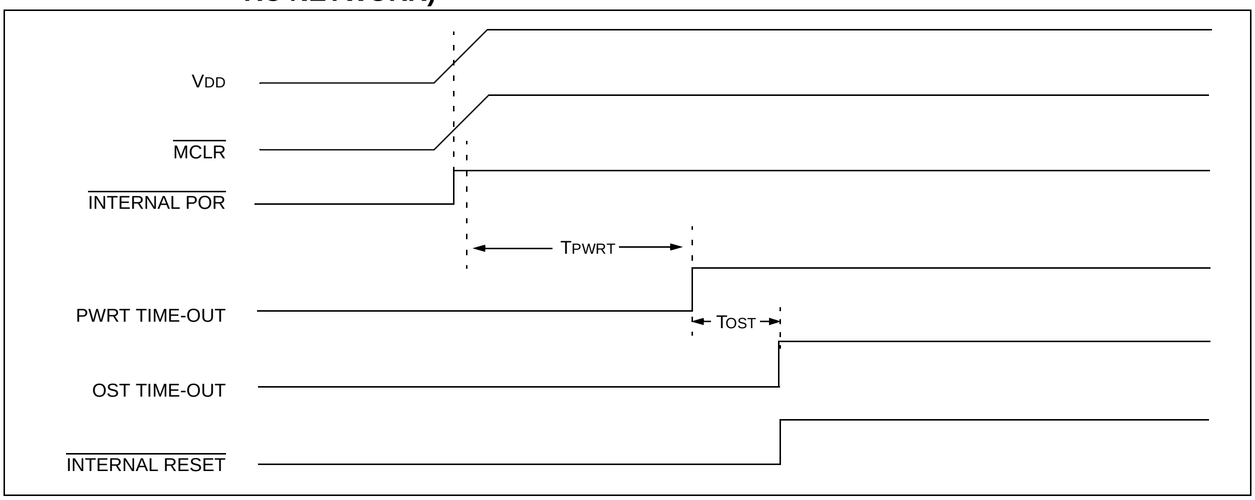


FIGURE 12-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

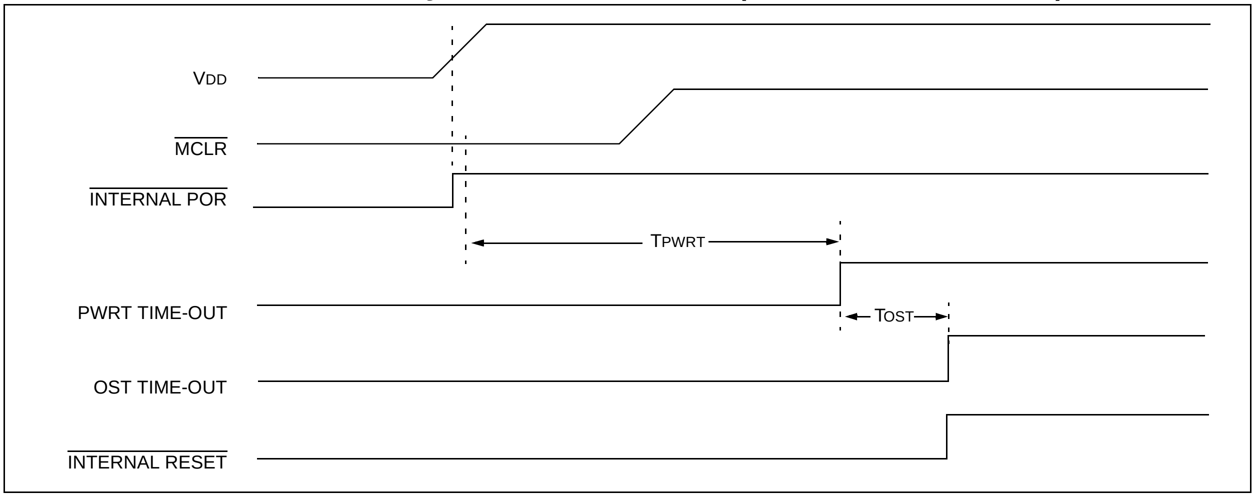


FIGURE 12-8: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

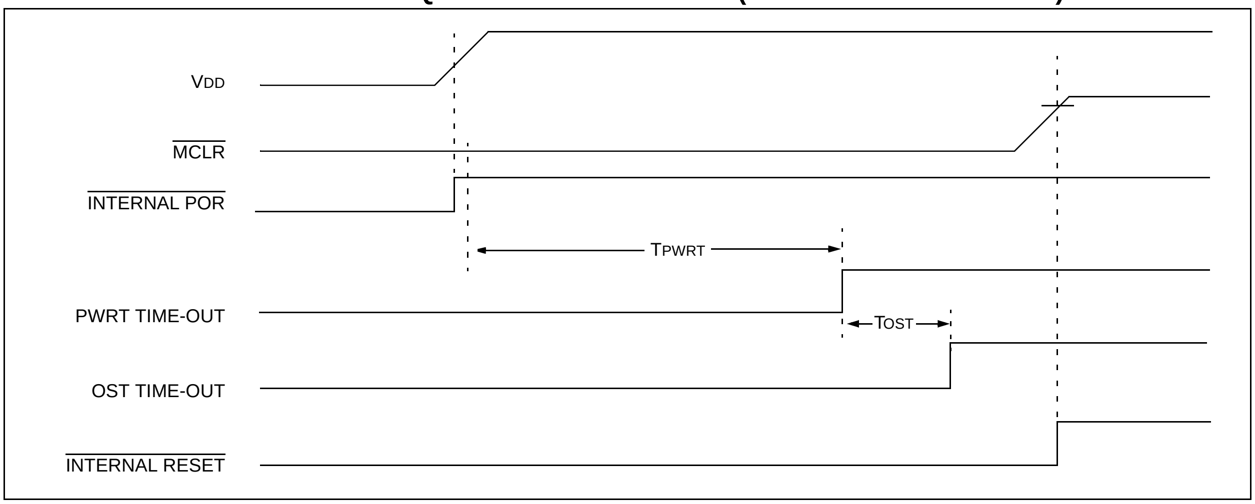
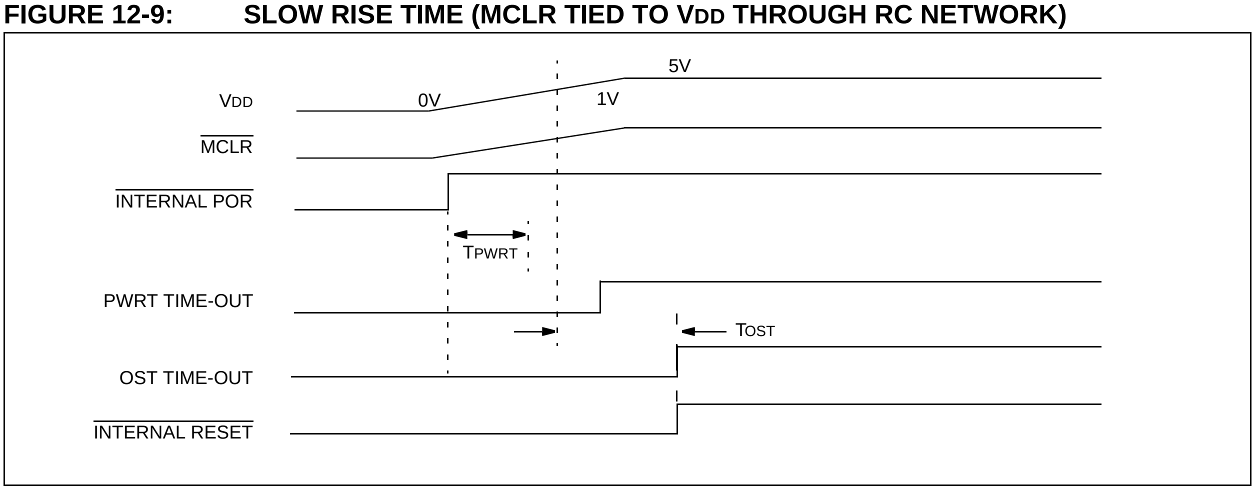


FIGURE 12-9: SLOW RISE TIME ($\overline{MCLR}$ TIED TO V_{DD} THROUGH RC NETWORK)



NOTES:

NOTES:

15.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias..-55 to +125°C

Storage temperature .... -65°C to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$. and RA4) .... -0.3V to (V_{DD} + 0.3V)

Voltage on V_{DD} with respect to V_{SS} .... -0.3 to +6.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ....0 to +13.5V

Voltage on RA4 with respect to Vss..0 to +12V

Total power dissipation **(Note 1)** 1.0W

Maximum current out of V_{SS} pin ....300 mA

Maximum current into V_{DD} pin ....250 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD})..± 20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ....± 20 mA

Maximum output current sunk by any I/O pin...25 mA

Maximum output current sourced by any I/O pin ....25 mA

Maximum current sunk by PORTA, PORTB, and PORTE (combined) **(Note 3)**..........................200 mA

Maximum current sourced by PORTA, PORTB, and PORTE (combined) **(Note 3)**......................200 mA

Maximum current sunk by PORTC and PORTD (combined) **(Note 3)** ....200 mA

Maximum current sourced by PORTC and PORTD (combined) **(Note 3)** ....200 mA

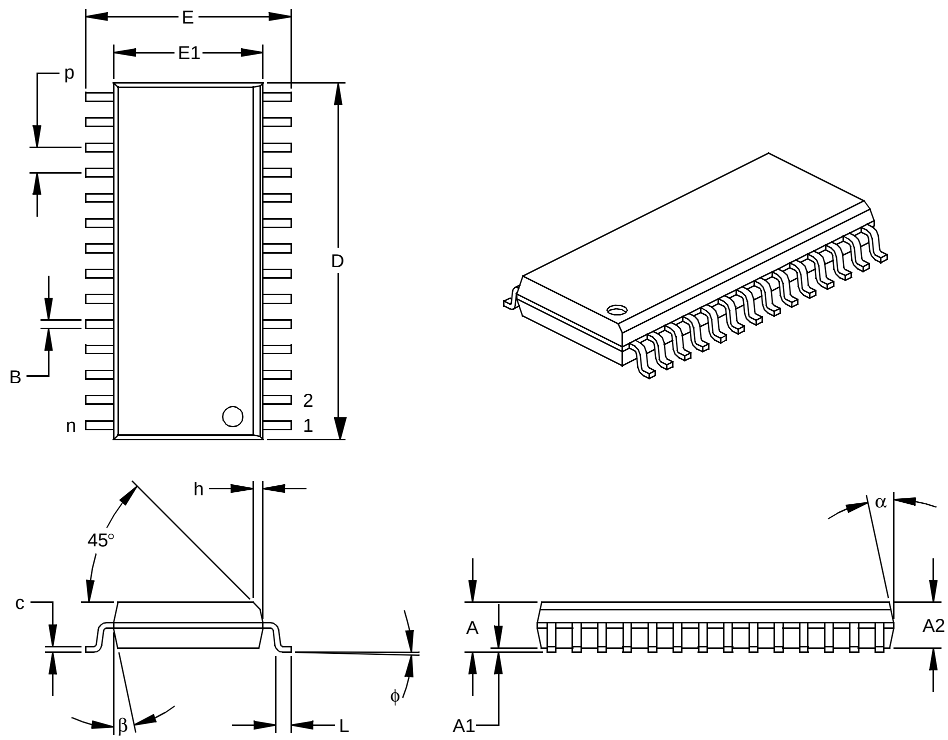
Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

2: Voltage spikes at the $\overline{MCLR}$ pin may cause latchup. A series resistor of greater than 1 kΩ should be used to pull $\overline{MCLR}$ to V_{DD}, rather than tying the pin directly to V_{DD}.

3: PORTD and PORTE are not implemented on the PIC16F73/76 devices.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

28-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

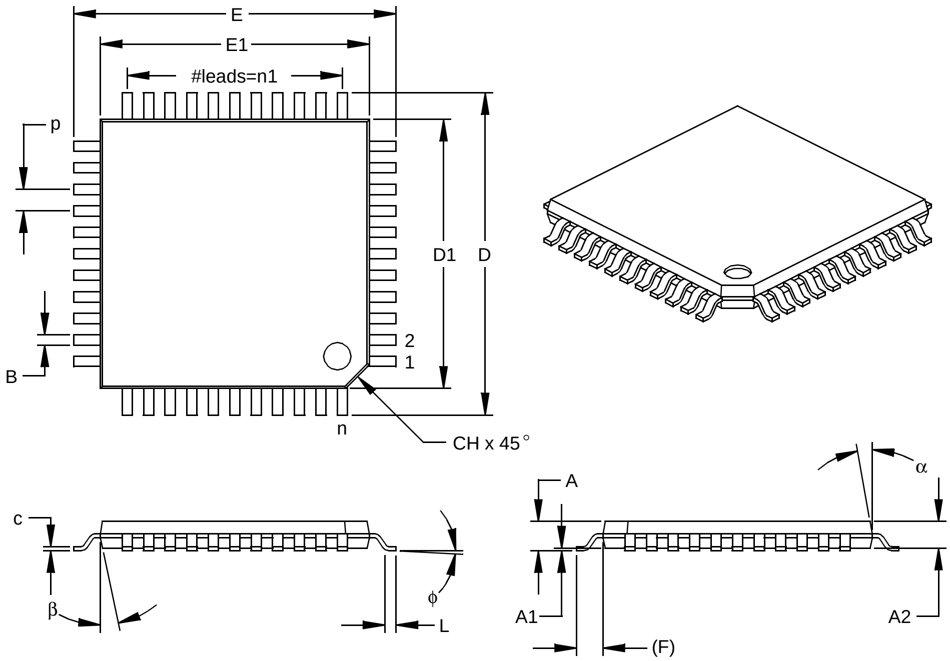


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-052

44-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.031			0.80	
Pins per Side	n1		11			11	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	(F)		.039		1.00		
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.463	.472	.482	11.75	12.00	12.25
Overall Length	D	.463	.472	.482	11.75	12.00	12.25
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.012	.015	.017	0.30	0.38	0.44
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-026
Drawing No. C04-076

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2000	This is a new data sheet. However, these devices are similar to the PIC16C7X devices found in the PIC16C7X Data Sheet (DS30390) or the PIC16F87X devices (DS30292).
B	2001	Final data sheet. Includes device characterization data. Addition of extended temperature devices. Addition of 28-pin MLF package. Minor typographic revisions throughout.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices in this data sheet are listed in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Difference	PIC16F73	PIC16F74	PIC16F76	PIC16F77
FLASH Program Memory (14-bit words)	4K	4K	8K	8K
Data Memory (bytes)	192	192	368	368
I/O Ports	3	5	3	5
A/D	5 channels, 8 bits	8 channels, 8 bits	5 channels, 8 bits	8 channels, 8 bits
Parallel Slave Port	no	yes	no	yes
Interrupt Sources	11	12	11	12
Packages	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC

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013001

PIC16F7X PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC16F7X(1), PIC16F7XT(1); VDD range 4.0V to 5.5V PIC16LF7X(1), PIC16LF7XT(1); VDD range 2.0V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	ML = MLF (Micro Lead Frame) PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny Plastic DIP P = PDIP L = PLCC SS = SSOP
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC16F77-I/P 301 = Industrial temp., PDIP package, normal VDD limits, QTP pattern #301.

b) PIC16LF76-I/SO = Industrial temp., SOIC package, Extended VDD limits.

c) PIC16F74-E/P = Extended temp., PDIP package, normal VDD limits.

Note 1: F = CMOS FLASH
LF = Low Power CMOS FLASH

2: T = in tape and reel - SOIC, PLCC, SSOP, TQFP packages only.

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Detroit
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Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Kokomo
2767 S. Albright Road
Kokomo, Indiana 46902
Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles
18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York
150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose
Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto
6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia
Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing
Microchip Technology Consulting (Shanghai) Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu
Microchip Technology Consulting (Shanghai) Co., Ltd., Chengdu Liaison Office
Rm. 2401, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou
Microchip Technology Consulting (Shanghai) Co., Ltd., Fuzhou Liaison Office
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506 Fax: 86-591-7503521

China - Shanghai
Microchip Technology Consulting (Shanghai) Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen
Microchip Technology Consulting (Shanghai) Co., Ltd., Shenzhen Liaison Office
Rm. 1315, 13/F, Shenzhen Kerry Centre,
Renminnan Lu
Shenzhen 518001, China
Tel: 86-755-2350361 Fax: 86-755-2366086

Hong Kong
Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India
Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaugnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan
Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea
Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore
Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-334-8870 Fax: 65-334-8850

Taiwan
Microchip Technology Taiwan
11F-3, No. 207
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Taipei, 105, Taiwan
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EUROPE

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Germany
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Italy
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Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom
Arizona Microchip Technology Ltd.
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Wokingham
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Tel: 44 118 921 5869 Fax: 44-118 921-5820

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